

※ **Cadmium:**

1. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC (*) amending Directive 76/769/EEC (**) relating to restrictions on the marketing and use of certain dangerous substances and preparations. (2005/747/EC)
2. Cadmium in optical and filter glass. (2005/747/EC)

※ **Mercury:**

1. Mercury in compact fluorescent lamps not exceeding 5 mg per lamp. (2002/95/EC)
2. Mercury in straight fluorescent lamps for general purposes not exceeding (2002/95/EC):
 - halophosphate 10 mg
 - triphosphate with normal lifetime 5 mg
 - triphosphate with long lifetime 8 mg
3. Mercury in straight fluorescent lamps for special purposes. (2002/95/EC)
4. Mercury in other lamps not specifically mentioned in this Annex. (2002/95/EC)

※ **Lead:**

1. Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead). (2005/747/EC)
2. lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications.(2005/747/EC)
3. lead in electronic ceramic parts (e.g. piezoelectronic devices). (2005/747/EC)
4. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes. (2002/95/EC)
5. Lead as an alloying element in steel containing up to 0.35% lead by weight, aluminium containing up to 0.4% lead by weight and as a copper alloy containing up to 4% lead by weight. (2002/95/EC)
6. Lead in lead-bronze bearing shells and bushes. (2005/717/EC)
7. Lead used in compliant pin connector systems. (2005/747/EC)
8. Lead as a coating material for the thermal conduction module c-ring. (2005/747/EC)
9. Lead in optical and filter glass. (2005/747/EC)
10. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight. (2005/747/EC)
11. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages. (2005/747/EC)

※ **Hexavalent – Chromium:**

1. Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators. (2002/95/EC)

※ **Deca-BDE:**

1. DecaBDE in polymeric applications. (2005/717/EC)

References: 2002/95/EC, 2005/717/EC, 2005/747/EC

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◇ **鎘 (Cadmium) :**

- 電接點(electrical contacts)的鎘及鎘化合物以及 91/338/EEC 指令限制範圍以外的鎘鍍層中的鎘。(2005/747/EC)
- 光學玻璃及濾光玻璃(optical and filter glass)中所用的鎘。(2005/747/EC)

◇ **六價鉻 (Hexavalent - Chromium) :**

- 電冰箱中作為碳鋼冷卻系統防腐劑的六價鉻。(2002/95/EC)

◇ **鉛 (Lead) :**

- 陰極射線管(cathode ray tubes)、電子部件(electronic components)和發光管(fluorescent tubes)等玻璃內的鉛含量。(2002/95/EC)
- 鋼中合金元素中的鉛含量達 0.35%、鋁含量達 0.4% , 銅合金中的鉛含量達 4%。(2002/95/EC)
- 高熔點錒錫中的鉛 (例如鉛含量 $\geq 85\%$ 的合金中的鉛)。(2005/747/EC)
- 用於伺服器(servers)、記憶體(storage)和存儲系統(storage array systems)和交換、信號和傳輸, 以及電信網路管理的網路基礎設施設備(network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications)中焊料的鉛。(2005/747/EC)
- 電子陶瓷產品中的鉛。(2005/747/EC)
- 用於鉛青銅軸承外殼(lead-bronze bearing shells and bushes)的鉛。(2005/717/EC)
- 光學玻璃及濾光玻璃(optical and filter glass)中所用的鉛。(2005/747/EC)
- 順應針連接系統(compliant pin connector systems)中使用的鉛。(2005/747/EC)
- 熱導槍釘模組(thermal conduction module c-ring)塗層中所用的鉛。(2005/747/EC)
- 微處理器針腳及封裝連接所使用含鉛量佔 80%-85%的焊接劑(含有超過兩種成份)中的鉛。(2005/747/EC)
- 用於焊接半導體終端和集成電路板載體的焊料中含鉛量。(2005/747/EC)

◇ **汞 (Mercury) :**

- 小型日光燈中不超過 5 mg / 燈管者。(2002/95/EC)
- 一般用途的直管日光燈管不超過(2002/95/EC) :
 - Halophosphate < 10 mg 。
 - Triphosphate with normal lifetime < 5 mg 。
 - Triphosphate with long lifetime < 8 mg 。
- 特殊用途的直管日光燈管。(2002/95/EC)
- 附件中未特別提及用於其他照明燈具的含汞量。(2002/95/EC)

◇ **十溴聯苯醚 (Deca-BDE)**

- 應用於高分子類(Polymeric)之十溴聯苯醚之含量。(2005/717/EC)

註:以上翻譯若有誤差, 應以原文法規為準。(請參考 2002/95/EC, 2005/717/EC, 2005/747/EC)

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